Liquid Rosin Flux

RoHS Compliant

Description

This is a rosin-based liquid flux with moderate activity. It is composed of pure Water White (WW) grade gum rosin in a unique solvent system with highly effective activators. Post soldering residues are nonconductive, non-corrosive, hydroscopic, non-tacky, and fungus resistant.

It can be used for both automated and manual soldering applications. It is great for general purpose soldering of PCBs, wire, cable and semiconductors. It is also ideal for solder coating or tinning leads. It may be applied by spray, foam, or wave fluxing for wave soldering applications.

Features and Benefits

- Meets IPC J-STD-004B and type ROM1
- For both leaded and lead-free solders
- Fast wetting
- Excellent foaming

Usage Parameters

Properties	Value
Shelf life	5 y
Storage temperature limits	18°C to 27°C [65°F to 80°F]

[a)] Store in a dry area, away from sunlight.

Properties

Flux Properties	Method	Value
Flux classification	J-STD-004B MIL-F-14256F	ROM1 RA
Flux type	J-STD-004B	Rosin
Flux activity	J-STD-004B	Moderate
Halides by weight	J-STD-004B	0.44%
Copper mirror	IPC-TM-650 2.3.32	Partial removal
Corrosion	IPC-TM-650 2.6.15	Pass
Cleaning requirements	-	Recommended
Physical Properties	**Method**	**Value**
Colour	Visual	Light amber
Solids %	IPC-TM-650 2.3.34	50%
Density	-	0.93 g/mL
Flash point	Closed cup	12°C [53°F]

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Application Instructions

1. Apply flux on the surface via dip, spray, foam, wave, or brush application.
2. Clean residue with flux removers.

Recommended Operating Parameters

Properties	Value
Amount of flux	Foam, wave: 1000 to 2000 µg/in2 solids Spray: 750 to 1500 µg/in2 solids
Foam fluxing parameters Foam stone pore size Flux level above stone Chimney opening Air pressure [a)]	 20 to 50 µm 25 to 40 mm [1 to 1.5 inch] 10 to 13 mm [3/8 to 1/2 inch] 1 to 2 lb/in^2
Top side preheat temperature	85°C to 110°C [190°F to 230°F]
Bottom side preheat temperature	35°C [65°F]
Conveyor speed	1.2 to 2.8 m/min [4 to 5 ft/min]
Contact time in solder (chip and lambda)	2.5 to 4.5 s
Solder pot temperature Sn96.5/Ag3.5 Sn95/Ag5 Sn99.3/Cu0.7 SnAgCu Sn95/Sb5	 260°C to 276°C [500°F to 530°F] 280°C to 296°C [536°F to 565°F] 265°C to 276°C [510°F to 530°F] 271°C to 276°C [520°F to 530°F] 280°C to 296°C [536°F to 565°F]

[a)] Adjust the air pressure to achieve the optimum foam height.

Packaging and Supporting Products

Part Number	Packaging	Net Volume	Net Weight	Packaged Weight
MC011532	Bottle	125 mL [4.22 fl oz]	116 g [4.10 oz]	140 g [0.31 lb]

Part Number Table

Description	Part Number
Rosin Flux, Bottle, 125ml	MC011532